# imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



### Contact us

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Messrs. Digi-Key

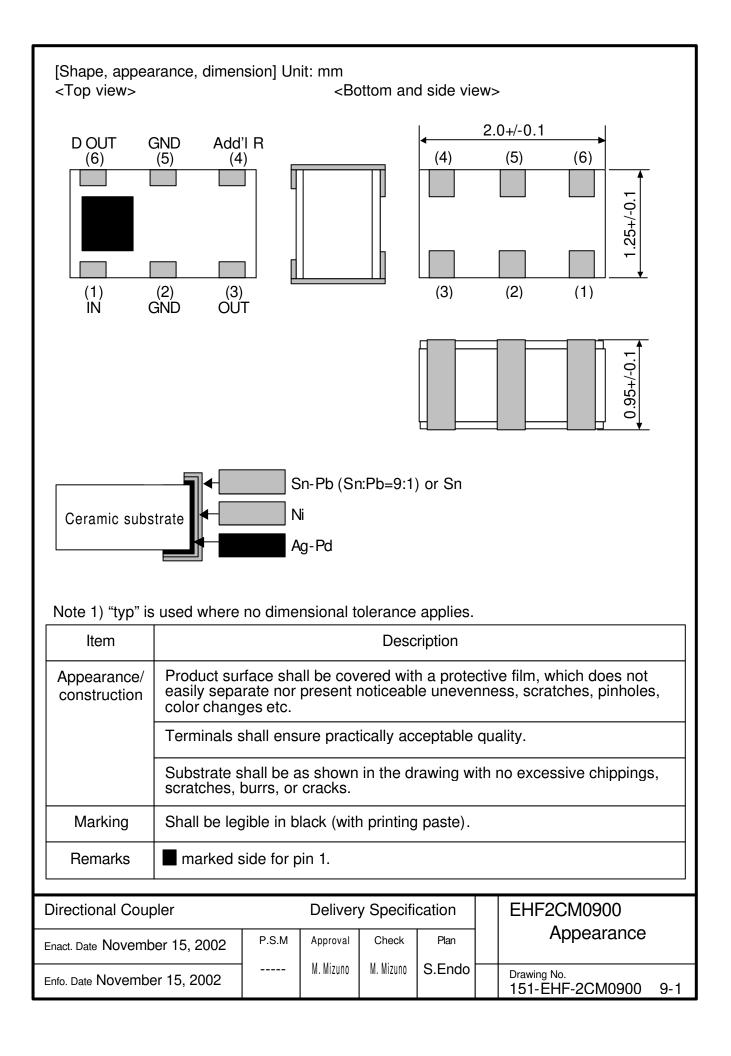
Issue No.: PC-02-044Date of issue : November 15, 2002Classification : ■ New □ Change □ Renewal

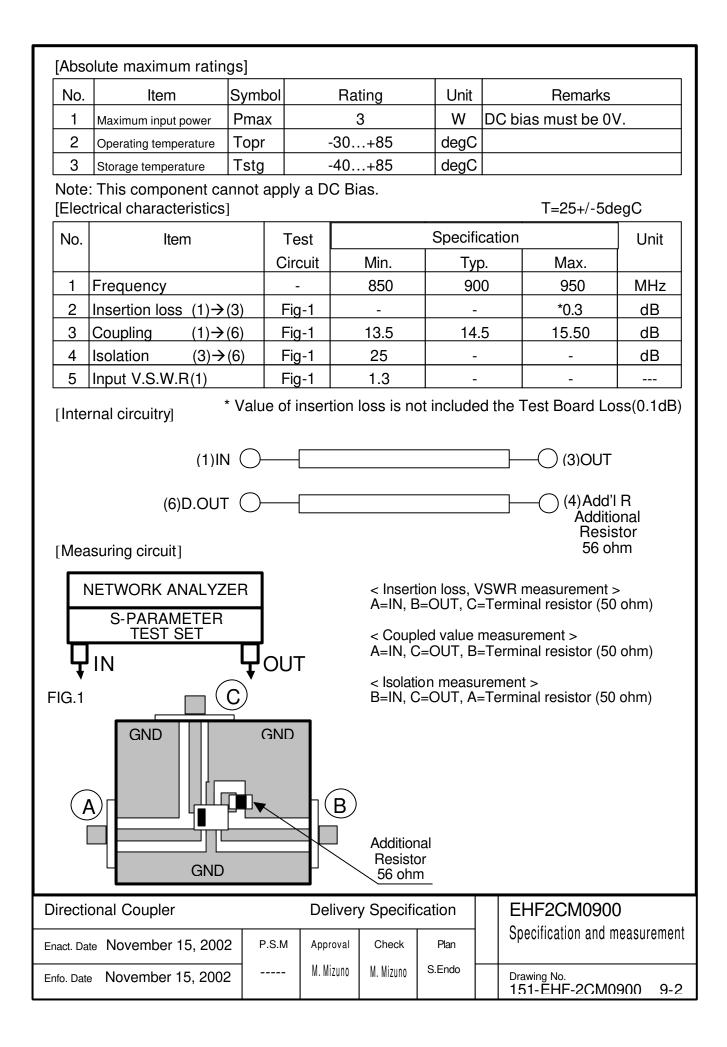
#### **Delivery Specification**

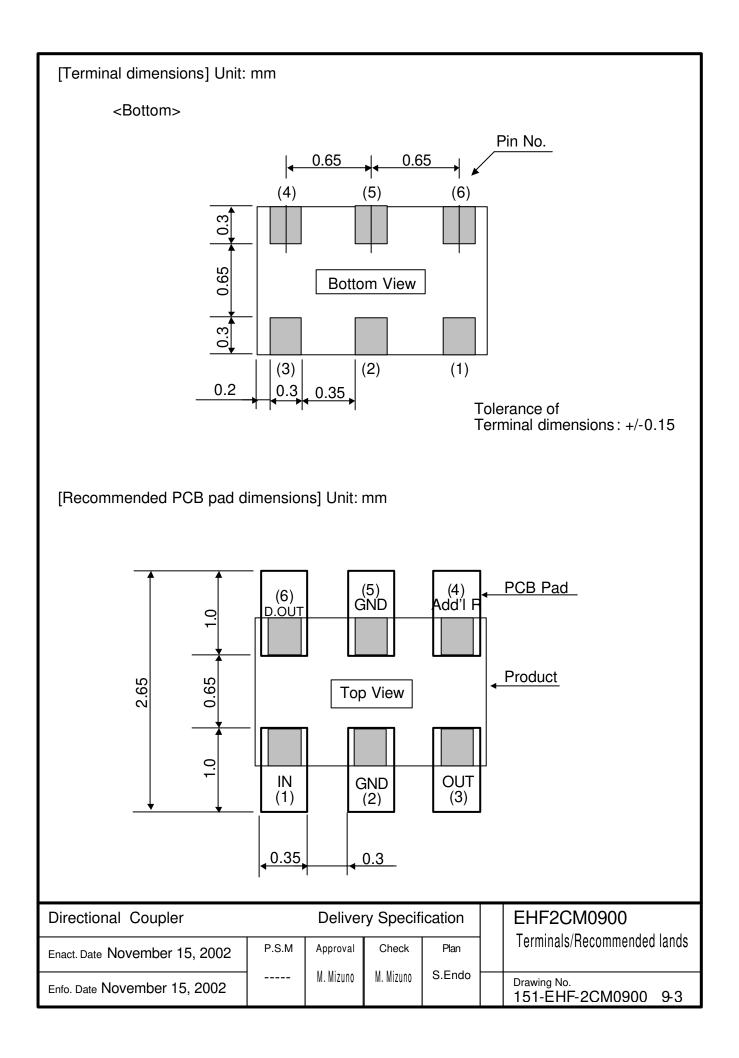
Product Description	: Directional Coupler
Product Part Number	: EHF2CM0900
Classification of Spec	: Individual Product Specification
Applications	: Cellular phone
	For other applications, contact the undersigned in advance.
Term of Validity	: November 14, 2007 from the date of issue.

CUSTOMER USE ONLY	Receipt Record#:	
This was certainly received by us. 1(one) copy is being returned to you.	Date of receipt:	
	Received by:	
	Title: Dept.:	

Matsushita Electronic Components Co., Ltd.		
Network Device Company	Prepared by	: S.Endo
Module Strategic Business Unit	Checked by	: M. Mizuno
Engineering Group HFD Team	• · · • • • • • • • • • • • • • • • • •	
992-1 Aiba Ohno-cho Ibi-gun Gifu 501-0598 JAPAN	Authorized by	: M. Mizuno
Tel: +81-0585-36-2322	Title	: Manager of Engineering
Fax: +81-0585-36-2344	THE	. Manager of Engineering







[Quality characteristic	s]						
Test item	Test condition	Judgment criteria					
High temperature	+85degC, 1000h	No abnormality shall be observed in					
Low temperature	-40degC, 1000h	appearance or					
High-temperature high-humidity storage	e high-humidity storage +60degC, 90%RH, 1000h						
Pressure Pot	+121degC, 99%RH, 2.026x10 <sup>5</sup> Pa, 100h	characteristics.					
Temperature cycling	-40+85degC, Each 30 min., 200cy						
Vibration	10500Hz, 10G, in each direction of XYZ, 2h30min.						
Impact	100G, 6mS, Half sinusoidal wave, in each direction of XYZ, 3 times						
Shock (Drop)	1.8m, 6 facesx6cy(36 times with 100g Dummy Load)						
Electro static discharge	200pF, 0 ohm, +/-200V, Each 5 times						
Soldering heat resistance	Manual hot gas: 260+/-10degC, 30 sec., 2 times	Over 90% of the terminal					
	Soldering iron: 260+/-10degC, 3 sec., 2 times	surface shall be covered with solder.					
	Reflow: 260degC peak, 2 times						
Solder ability	Solder bath: 235+/-5degC, 2 sec.	Over 95% of the terminal					
	Reflow: 230degC	surface shall be covered with solder.					
Board warping	Assemble this component on a PC board with 0.8mm thickness using the recommended soldering condition shown below, and apply a bending force of 3mm warping at a rate of 1mm/sec. 5 seconds and 5 times. t=0.8mm	There should not be any cracks in the component or solder joints, no abnormality in electrical characteristics.					
Terminal removal	Solder a component on a PC board using the recommended of then press the component sideways at 1mm/sec. Destruction lir						
Seating plane co-planarity	Within 0.1mm						
< Recommended sold Diagram1 Shown b degC 250 230 230 200 170 140	ering condition > below is a recommended reflow soldering conditio	n.					
30~60 sec. 60~180 sec. Time							
Directional Coupler Delivery Specification EHF2CM0900							
Enact. Date November 15, 2		lity Characteristics					
Enfo. Date November 15, 20	002 M. Mizuno M. Mizuno S.Endo Drawin 151-	<sub>g №.</sub> EHF-2CM0900 9-4					

[Cautions for use]

(1) Operating a product over the maximum rating for even a moment	may result in a
product failure or breakage. Never use a product in such a condit	ion that it may
cause a safety problem.	

- (2) Opening or short-circuiting the product terminals or inserting a product in the reverse orientation while power is being supplied may cause a breakage. Always avoid such circumstances.
- (3) Operations in a corrosive gas atmosphere or improper environments such as hightemperature, high-humidity or dewy conditions may lead to product performance deterioration, a breakage, a change in appearance etc. Please avoid such conditions, as they are unsafe.
- (4) Always ground the soldering iron or soldering bath used for assembly operation to avoid any excessive voltage applied to a product.
- (5) After soldering with solder bridges, incomplete soldering or in the reverse orientation, supplying power may result in a product breakage. Please confirm the soldered condition before supplying power to the product.
- (6) Excessive stress on the terminals may cause a contact failure or performance deterioration. Please use caution.
- (7) Please provide a fail-safe provision in the product you design by taking any failure of our product into consideration.
- (8) This product does not include a DC-cutting device. Application of a DC Current may cause product deterioration or breakage.
  - \* If any question arises about the safety of this product, please contact us immediately with a request for an engineering examination.

#### [Remarks]

- \*1: All of the materials used in this product are those listed as the existing chemical substances based on the "Law for examination and regulation of manufacture of chemical substances".
- \*2: The production process of this product does not use any ozone-depleting chemicals (OZC) regulated by the Montreal Protocol.
- \*3: Validity of this specification is 5 years from the date of issue, but the validity is considered on going unless any changes are made.

Directional Coupler Delivery Specification			EHF2CM0900		
Enact. Date November 15, 2002	P.S.M	Approval	Check	Plan	Cautions
Enfo. Date November 15, 2002		M. Mizuno	M. Mizuno	S.Endo	Drawing No. 151-EHF-2CM0900 9-5

## [Packaging materials] 1. Materials 1)

- 1) Embossed carrier tape (Refer to the attachment)
  2) Top tape: Anti-static
  3) Packaging box (Refer to the attachment)
  4) Packaging tape, carrier-securing adhesive tape

- 2. Specification

	•	1						
No.	Item	Condition						Remarks
1	Reel outer diameter	Refer to	the att					
2	Reel inner diameter	Refer to	the att					
3	Reel inner width	Refer to	the att	<u>achment</u>				
4	Quantity in a reel	4000 pi	eces/re	el				
5	Taping direction						ling direction ngs facing up)	
6	Top tape attachment position	Top tape e	e attachm edge mus	ent area > t stay inside les shall no		5.5mn Emb	tape	Tape breaks force. Min. 10N Top cover tape strength. Min. 10N Tape peel force. 0.11.0N Tape peel angle. 165180degree Reel weight. Max 1500g
7	Label attachment position			Indicated Item Pat No., Lot No. Quantity, Maker Country of Origin				
8	Tape leader part and tape ending part	200	→ Prod ~220mm unloaded p		10~150mm, 1	Leader	Top tape	
9								
							84000 pieces/box(Max)	
Dire						CM0900 ging specification 1		
Enact. Date November 15, 2002								
Enfo.	Enfo. Date November 15, 2002 Drawing No. 151-EHF-2CM0900 9-6						Drawing N 151-E	

